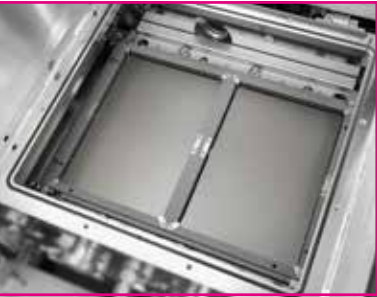


Batch soldering systems VADU 200 XL and VADU 200 XL-W

Vacuum supported soldering of substrates and wafers



View into the process chamber of VADU 200 XL.



View into the process chamber of VADU 200 XL-W.

The soldering systems of type VADU 200 XL are equipped with two separate process chambers and can be operated with paste as well as preforms.

The VADU 200 XL-W enables the soldering of wafers up to 12". Therefore PiNK produces also customized carriers.

Both soldering systems allow the precise control of all relevant process parameters e.g. the temperature gradients during heating and cooling. Due to its intelligent temperature management the system provides short cycle times and an excellent temperature stability.

System features

- Void-free solder connections
- Soldering with preforms and/or pastes
- Individual soldering profiles
- Soldering temperatures up to 400 °C
- Controlled temperature gradients
- Short cycle times
- Separate soldering and cooling chamber
- Formic acid process
- Flux management
- Inert gas atmosphere
- Residual oxygen content < 5 ppm
- Reproducibility of the soldering results
- Traceability
- Permanent process control
- USB connection
- Ethernet interface
- Remote maintenance (VPN)
- Low energy and media consumption
- Internationally patented system

Options

- Wafer up to 12"
- Induction heating
- High vacuum
- Handling/Transfer systems

Technical data

Process area VADU 200 XL (W x D): 410 x 280 mm (e.g. 4 cards à 5 x 7")

Clearance height: max. 100 mm

Dimensions of the system (W x D x H): 1,200 x 2,110 x 1,700 mm

Power supply: 3 x 400 V, 50/60 Hz

Power input: 10 kVA

Weight VADU 200 XL: 1,200 kg, Weight VADU 200 XL-W: 1,400 kg



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